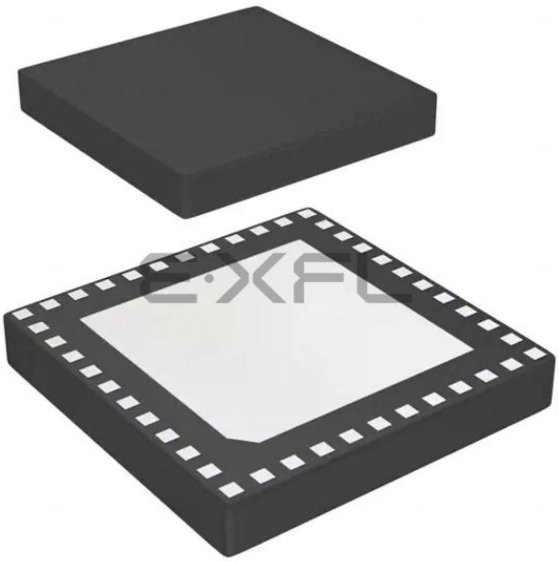

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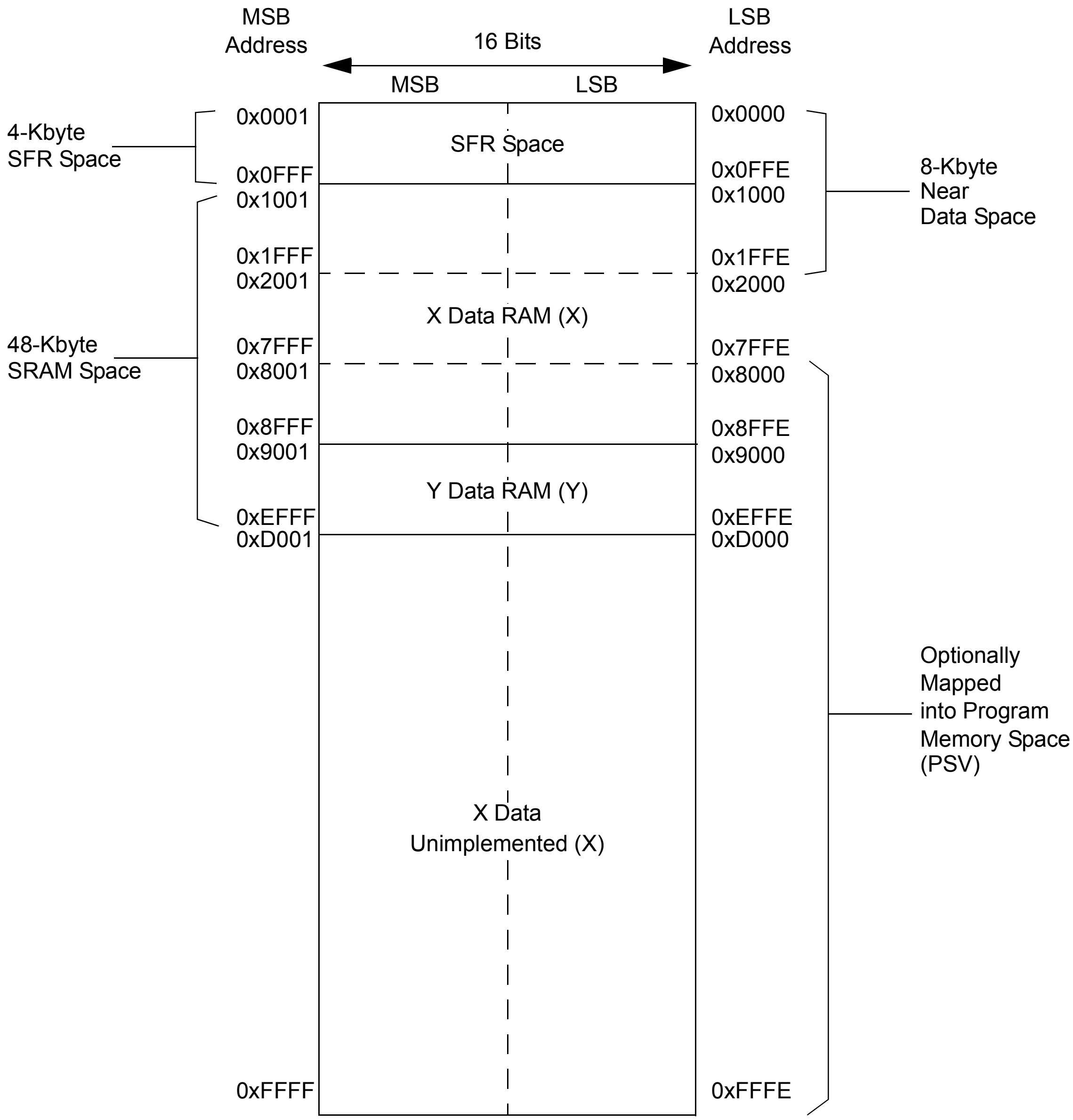
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512mc204-e-tl

FIGURE 4-11: DATA MEMORY MAP FOR dsPIC33EP512MC20X/50X AND dsPIC33EP512GP50X DEVICES



Note: Memory areas are not shown to scale.

4.8 Interfacing Program and Data Memory Spaces

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture uses a 24-bit-wide Program Space (PS) and a 16-bit-wide Data Space (DS). The architecture is also a modified Harvard scheme, meaning that data can also be present in the Program Space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Aside from normal execution, the architecture of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provides two methods by which Program Space can be accessed during operation:

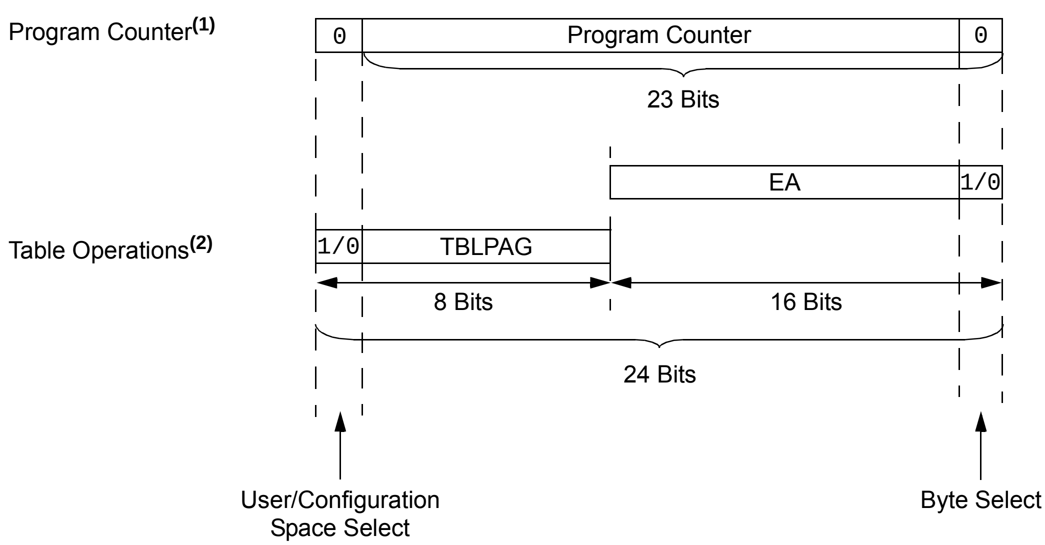
- Using table instructions to access individual bytes or words anywhere in the Program Space
- Remapping a portion of the Program Space into the Data Space (Program Space Visibility)

Table instructions allow an application to read or write to small areas of the program memory. This capability makes the method ideal for accessing data tables that need to be updated periodically. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for look-ups from a large table of static data. The application can only access the least significant word of the program word.

TABLE 4-65: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	`0`	PC<22:1>			`0`
		`0xx xxxx xxxx xxxx xxxx xxx0`				
`TBLRD/TBLWT` (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		`0xxx xxxx`		`xxxx xxxx xxxx xxxx`		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		`1xxx xxxx`		`xxxx xxxx xxxx xxxx`		

FIGURE 4-22: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The Least Significant bit (LSb) of Program Space addresses is always fixed as ‘`0`’ to maintain word alignment of data in the Program and Data Spaces.

2: Table operations are not required to be word-aligned. Table Read operations are permitted in the configuration memory space.

6.1 Reset Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

6.1.1 KEY RESOURCES

- **"Reset"** (DS70602) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 8-2: DMAxREQ: DMA CHANNEL x IRQ SELECT REGISTER

R/S-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
FORCE(1)	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IRQSEL7	IRQSEL6	IRQSEL5	IRQSEL4	IRQSEL3	IRQSEL2	IRQSEL1	IRQSEL0
bit 7							bit 0

Legend:	S = Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FORCE:** Force DMA Transfer bit(1)
1 = Forces a single DMA transfer (Manual mode)
0 = Automatic DMA transfer initiation by DMA request

bit 14-8 **Unimplemented:** Read as '0'

bit 7-0 **IRQSEL<7:0>:** DMA Peripheral IRQ Number Select bits
01000110 = ECAN1 – TX Data Request(2)
00100110 = IC4 – Input Capture 4
00100101 = IC3 – Input Capture 3
00100010 = ECAN1 – RX Data Ready(2)
00100001 = SPI2 Transfer Done
00011111 = UART2TX – UART2 Transmitter
00011110 = UART2RX – UART2 Receiver
00011100 = TMR5 – Timer5
00011011 = TMR4 – Timer4
00011010 = OC4 – Output Compare 4
00011001 = OC3 – Output Compare 3
00001101 = ADC1 – ADC1 Convert done
00001100 = UART1TX – UART1 Transmitter
00001011 = UART1RX – UART1 Receiver
00001010 = SPI1 – Transfer Done
00001000 = TMR3 – Timer3
00000111 = TMR2 – Timer2
00000110 = OC2 – Output Compare 2
00000101 = IC2 – Input Capture 2
00000010 = OC1 – Output Compare 1
00000001 = IC1 – Input Capture 1
00000000 = INT0 – External Interrupt 0

Note 1: The FORCE bit cannot be cleared by user software. The FORCE bit is cleared by hardware when the forced DMA transfer is complete or the channel is disabled (CHEN = 0).
2: This selection is available in dsPIC33EPXXXGP/MC50X devices only.

REGISTER 8-12: DMARQC: DMA REQUEST COLLISION STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **RQCOL3:** DMA Channel 3 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

bit 2 **RQCOL2:** DMA Channel 2 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

bit 1 **RQCOL1:** DMA Channel 1 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

bit 0 **RQCOL0:** DMA Channel 0 Transfer Request Collision Flag bit
1 = User force and interrupt-based request collision is detected
0 = No request collision is detected

11.7 Peripheral Pin Select Registers

REGISTER 11-1: RPINR0: PERIPHERAL PIN SELECT INPUT REGISTER 0

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INT1R<6:0>						
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **INT1R<6:0>:** Assign External Interrupt 1 (INT1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7-0 **Unimplemented:** Read as ‘0’

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected Fault input
0 = Leading-Edge Blanking is not applied to selected Fault input

bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected current-limit input
0 = Leading-Edge Blanking is not applied to selected current-limit input

bit 9-6 **Unimplemented:** Read as '0'

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
0 = No blanking when PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
0 = No blanking when PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
0 = No blanking when PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

17.0 QUADRATURE ENCODER INTERFACE (QEI) MODULE (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Quadrature Encoder Interface (QEI)"** (DS70601) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This chapter describes the Quadrature Encoder Interface (QEI) module and associated operational modes. The QEI module provides the interface to incremental encoders for obtaining mechanical position data.

The operational features of the QEI module include:

- 32-Bit Position Counter
- 32-Bit Index Pulse Counter
- 32-Bit Interval Timer
- 16-Bit Velocity Counter
- 32-Bit Position Initialization/Capture/Compare High register
- 32-Bit Position Compare Low register
- x4 Quadrature Count mode
- External Up/Down Count mode
- External Gated Count mode
- External Gated Timer mode
- Internal Timer mode

Figure 17-1 illustrates the QEI block diagram.

REGISTER 17-2: QEI1IOC: QEI1 I/O CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QCAPEN	FLTREN	QFDIV2	QFDIV1	QFDIV0	OUTFNC1	OUTFNC0	SWPAB
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R-x	R-x	R-x	R-x
HOMPOL	IDXPOL	QEBPOL	QEAPOL	HOME	INDEX	QEB	QEA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**QCAPEN:** QEI Position Counter Input Capture Enable bit 1 = Index match event triggers a position capture event 0 = Index match event does not trigger a position capture event
bit 14	**FLTREN:** QEAx/QEBx/INDXx/HOMEx Digital Filter Enable bit 1 = Input pin digital filter is enabled 0 = Input pin digital filter is disabled (bypassed)
bit 13-11	**QFDIV<2:0>:** QEAx/QEBx/INDXx/HOMEx Digital Input Filter Clock Divide Select bits 111 = 1:128 clock divide 110 = 1:64 clock divide 101 = 1:32 clock divide 100 = 1:16 clock divide 011 = 1:8 clock divide 010 = 1:4 clock divide 001 = 1:2 clock divide 000 = 1:1 clock divide
bit 10-9	**OUTFNC<1:0>:** QEI Module Output Function Mode Select bits 11 = The CTNCMPx pin goes high when QEI1LEC ≥ POS1CNT ≥ QEI1GEC 10 = The CTNCMPx pin goes high when POS1CNT ≤ QEI1LEC 01 = The CTNCMPx pin goes high when POS1CNT ≥ QEI1GEC 00 = Output is disabled
bit 8	**SWPAB:** Swap QEA and QEB Inputs bit 1 = QEAx and QEBx are swapped prior to quadrature decoder logic 0 = QEAx and QEBx are not swapped
bit 7	**HOMPOL:** HOMEx Input Polarity Select bit 1 = Input is inverted 0 = Input is not inverted
bit 6	**IDXPOL:** INDXx Input Polarity Select bit 1 = Input is inverted 0 = Input is not inverted
bit 5	**QEBPOL:** QEBx Input Polarity Select bit 1 = Input is inverted 0 = Input is not inverted
bit 4	**QEAPOL:** QEAx Input Polarity Select bit 1 = Input is inverted 0 = Input is not inverted
bit 3	**HOME:** Status of HOMEx Input Pin After Polarity Control 1 = Pin is at logic ‘1’ 0 = Pin is at logic ‘0’

REGISTER 17-19: INT1HLDH: INTERVAL 1 TIMER HOLD HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **INTHLD<31:16>:** Hold Register for Reading and Writing INT1TMRH bits

REGISTER 17-20: INT1HLDL: INTERVAL 1 TIMER HOLD LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
INTHLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **INTHLD<15:0>:** Hold Register for Reading and Writing INT1TMRL bits

REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN(2)	CKP	MSTEN	SPRE2(3)	SPRE1(3)	SPRE0(3)	PPRE1(3)	PPRE0(3)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **DISSCK:** Disable SCKx Pin bit (SPIx Master modes only)
1 = Internal SPIx clock is disabled, pin functions as I/O
0 = Internal SPIx clock is enabled

bit 11 **DISSDO:** Disable SDOx Pin bit
1 = SDOx pin is not used by the module; pin functions as I/O
0 = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master mode:
1 = Input data is sampled at end of data output time
0 = Input data is sampled at middle of data output time
Slave mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** SPIx Clock Edge Select bit(1)
1 = Serial output data changes on transition from active clock state to Idle clock state (refer to bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (refer to bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)
1 = $\overline{\text{SSx}}$ pin is used for Slave mode
0 = $\overline{\text{SSx}}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to ‘0’ for Framed SPI modes (FRMEN = 1).
2: This bit must be cleared when FRMEN = 1.
3: Do not set both primary and secondary prescalers to the value of 1:1.

REGISTER 19-2: I2CxSTAT: I2Cx STATUS REGISTER

R-0, HSC	R-0, HSC	U-0	U-0	U-0	R/C-0, HS	R-0, HSC	R-0, HSC
ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10
bit 15							bit 8

R/C-0, HS	R/C-0, HS	R-0, HSC	R/C-0, HSC	R/C-0, HSC	R-0, HSC	R-0, HSC	R-0, HSC
IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HSC = Hardware Settable/Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ACKSTAT:** Acknowledge Status bit (when operating as I²C™ master, applicable to master transmit operation)
1 = NACK received from slave
0 = ACK received from slave
Hardware is set or clear at the end of slave Acknowledge.

bit 14 **TRSTAT:** Transmit Status bit (when operating as I²C master, applicable to master transmit operation)
1 = Master transmit is in progress (8 bits + ACK)
0 = Master transmit is not in progress
Hardware is set at the beginning of master transmission. Hardware is clear at the end of slave Acknowledge.

bit 13-11 **Unimplemented:** Read as ‘0’

bit 10 **BCL:** Master Bus Collision Detect bit
1 = A bus collision has been detected during a master operation
0 = No bus collision detected
Hardware is set at detection of a bus collision.

bit 9 **GCSTAT:** General Call Status bit
1 = General call address was received
0 = General call address was not received
Hardware is set when address matches general call address. Hardware is clear at Stop detection.

bit 8 **ADD10:** 10-Bit Address Status bit
1 = 10-bit address was matched
0 = 10-bit address was not matched
Hardware is set at the match of the 2nd byte of the matched 10-bit address. Hardware is clear at Stop detection.

bit 7 **IWCOL:** I2Cx Write Collision Detect bit
1 = An attempt to write to the I2CxTRN register failed because the I²C module is busy
0 = No collision
Hardware is set at the occurrence of a write to I2CxTRN while busy (cleared by software).

bit 6 **I2COV:** I2Cx Receive Overflow Flag bit
1 = A byte was received while the I2CxRCV register was still holding the previous byte
0 = No overflow
Hardware is set at an attempt to transfer I2CxRSR to I2CxRCV (cleared by software).

bit 5 **D_A:** Data/Address bit (when operating as I²C slave)
1 = Indicates that the last byte received was data
0 = Indicates that the last byte received was a device address
Hardware is clear at a device address match. Hardware is set by reception of a slave byte.

bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware is set or clear when a Start, Repeated Start or Stop is detected.

REGISTER 23-5: AD1CHS123: ADC1 INPUT CHANNEL 1, 2, 3 SELECT REGISTER (CONTINUED)

bit 0 **CH123SA:** Channel 1, 2, 3 Positive Input Select for Sample MUXA bit

In 12-bit mode (AD21B = 1), CH123SA is Unimplemented and is Read as '0':

Value	ADC Channel		
	CH1	CH2	CH3
1(2)	OA1/AN3	OA2/AN0	OA3/AN6
0(1,2)	OA2/AN0	AN1	AN2

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias .... -40°C to +125°C
Storage temperature .... -65°C to +150°C
Voltage on VDD with respect to VSS .... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS(3) .... -0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD $\geq$ 3.0V(3) .... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to Vss when VDD < 3.0V(3) .... -0.3V to +3.6V
Maximum current out of VSS pin .... 300 mA
Maximum current into VDD pin(2) .... 300 mA
Maximum current sunk/sourced by any 4x I/O pin .... 15 mA
Maximum current sunk/sourced by any 8x I/O pin .... 25 mA
Maximum current sunk by all ports(2,4) .... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

4: Exceptions are: dsPIC33EPXXXGP502, dsPIC33EPXXXMC202/502 and PIC24EPXXXGP/MC202 devices, which have a maximum sink/source capability of 130 mA.

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage**	3.0	—	3.6	V	
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.03	—	—	V/ms	0V-1V in 100 ms

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-5: FILTER CAPACITOR (CEFC) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated): Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
	CEFC	External Filter Capacitor Value(1)	4.7	10	—	μF	Capacitor must have a low series resistance (< 1 Ohm)

Note 1: Typical VCAP voltage = 1.8 volts when VDD ≥ VDDMIN.

TABLE 30-46: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of FP or 11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-60: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	T_{AD}	ADC Clock Period	117.6	—	—	ns	
AD51	t_{RC}	ADC Internal RC Oscillator Period(2)	—	250	—	ns	
Conversion Rate							
AD55	t_{CONV}	Conversion Time	—	14 T_{AD}		ns	
AD56	F_{CNV}	Throughput Rate	—	—	500	ksps	
AD57a	T_{SAMP}	Sample Time when Sampling any ANx Input	3 T_{AD}	—	—	—	
AD57b	T_{SAMP}	Sample Time when Sampling the Op Amp Outputs (Configuration A and Configuration B)(4,5)	3 T_{AD}	—	—	—	
Timing Parameters							
AD60	t_{PCS}	Conversion Start from Sample Trigger(2,3)	2 T_{AD}	—	3 T_{AD}	—	Auto-convert trigger is not selected
AD61	t_{PSS}	Sample Start from Setting Sample (SAMP) bit(2,3)	2 T_{AD}	—	3 T_{AD}	—	
AD62	t_{CSS}	Conversion Completion to Sample Start (ASAM = 1)(2,3)	—	0.5 T_{AD}	—	—	
AD63	t_{DPU}	Time to Stabilize Analog Stage from ADC Off to ADC On(2,3)	—	—	20	μs	**(Note 6)**

Note 1: Device is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: Parameters are characterized but not tested in manufacturing.

3: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

4: See Figure 25-6 for configuration information.

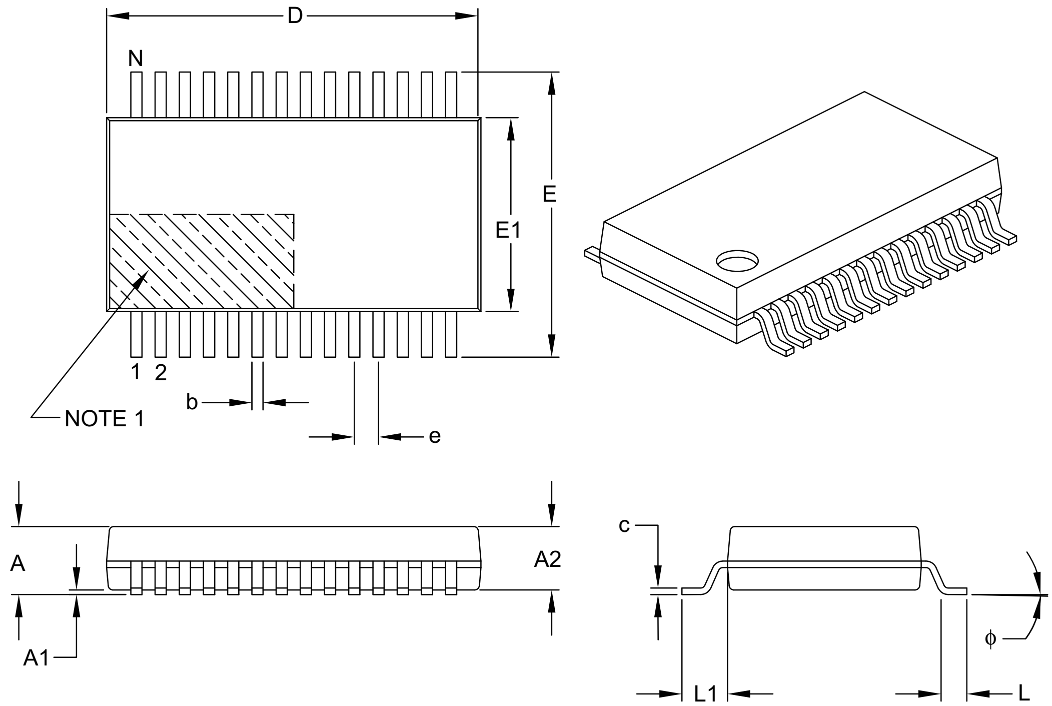
5: See Figure 25-7 for configuration information.

6: The parameter, t_{DPU}, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (AD1CON1<15>) = 1). During this time, the ADC result is indeterminate.

NOTES:

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

Revision H (August 2013)

This revision includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-6.

TABLE A-6: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Adds Peripheral Pin Select (PPS) to allow Digital Function Remapping and Change Notification Interrupts to Input/Output section • Adds heading information to 64-Pin TQFP
Section 4.0 “Memory Organization”	• Corrects Reset values for ANSELE, TRISF, TRISC, ANSELC and TRISA • Corrects address range from 0x2FFF to 0x7FFF • Corrects DSRPAG and DSWPAG (now 3 hex digits) • Changes Call Stack Frame from <15:1> to PC<15:0> • Word length in Figure 4-20 is changed to 50 words for clarity
Section 5.0 “Flash Program Memory”	• Corrects descriptions of NVM registers
Section 9.0 “Oscillator Configuration”	• Removes resistor from Figure 9-1 • Adds Fast RC Oscillator with Divide-by-16 (FRCDIV16) row to Table 9-1 • Removes incorrect information from ROI bit in Register 9-2
Section 14.0 “Input Capture”	• Changes 31 user-selectable Trigger/Sync interrupts to 19 user-selectable Trigger/ Sync interrupts • Corrects ICTSEL<12:10> bits (now ICTSEL<2:0>)
Section 17.0 “Quadrature Encoder Interface (QEI) Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)”	• Corrects QCAPEN bit description
Section 19.0 “Inter-Integrated Circuit™ (I^2C™)”	• Adds note to clarify that 100kbit/sec operation of I^2C is not possible at high processor speeds
Section 22.0 “Charge Time Measurement Unit (CTMU)”	• Clarifies Figure 22-1 to accurately reflect peripheral behavior
Section 23.0 “10-Bit/12-Bit Analog-to-Digital Converter (ADC)”	• Correct Figure 23-1 (changes CH123x to CH123Sx)
Section 24.0 “Peripheral Trigger Generator (PTG) Module”	• Adds footnote to Register 24-1 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled.
Section 25.0 “Op Amp/ Comparator Module”	• Adds note to Figure 25-3 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled) • Adds footnote to Register 25-2 (COE is not available when OPMODE (CMxCON<10>) = 1)
Section 27.0 “Special Features”	• Corrects the bit description for FNOSC<2:0>
Section 30.0 “Electrical Characteristics”	• Corrects 512K part power-down currents based on test data • Corrects WDT timing limits based on LPRC oscillator tolerance
Section 31.0 “High-Temperature Electrical Characteristics”	• Adds Table 31-5 (DC Characteristics: Idle Current (I_{IDLE})